

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units	
Peak Inverse Voltage	V_{RWM}	-	60	V	
Max. Average Forward Current	$I_{F(AV)}$	50% duty cycle @ $T_C=109^{\circ}C$, rectangular wave form	200	per leg	A
			400	per device	
Max. Peak One Cycle Non-Repetitive Surge Current (per leg)	I_{FSM}	8.3 ms, half Sine pulse	3960	A	
Non-Repetitive Avalanche Energy(per leg)	E_{AS}	$T_J=25^{\circ}C, I_{AS}=1A, L=30mH$	15	mJ	
Repetitive Avalanche Current(per leg)	I_{AR}	Current decaying linearly to zero in 1 μ sec Frequency limited by T_J max. $V_A=1.5 \times V_R$ typical	1	A	

Electrical Characteristics:

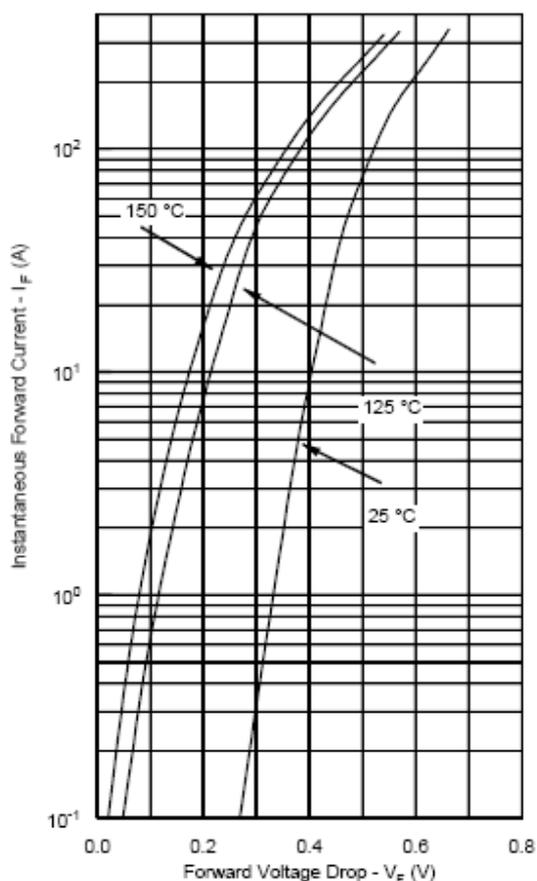
Characteristics	Symbol	Condition	Max.	Units
Max. Forward Voltage Drop (per leg) *	V_{F1}	@ 200A, Pulse, $T_J = 25^{\circ}C$ @ 400A, Pulse, $T_J = 25^{\circ}C$	0.68 0.83	V
	V_{F2}	@ 200A, Pulse, $T_J = 125^{\circ}C$ @ 400A, Pulse, $T_J = 125^{\circ}C$	0.59 0.76	V
Max. Reverse Current (per leg) *	I_{R1}	@ $V_R =$ rated V_R $T_J = 25^{\circ}C$	2.2	mA
	I_{R2}	@ $V_R =$ rated V_R $T_J = 125^{\circ}C$	600	mA
Max. Junction Capacitance (per leg)	C_T	@ $V_R = 5V, T_C = 25^{\circ}C$ $f_{SIG} = 1MHz$	11000	pF
Typical Series Inductance (per leg)	L_S	Measured lead to lead 5 mm from package body	5.0	nH
Max. Voltage Rate of Change	dv/dt	-	10,000	V/ μ s
Insulation Voltage	V_{RMS}	-	1000	V

* Pulse Width < 300 μ s, Duty Cycle <2%

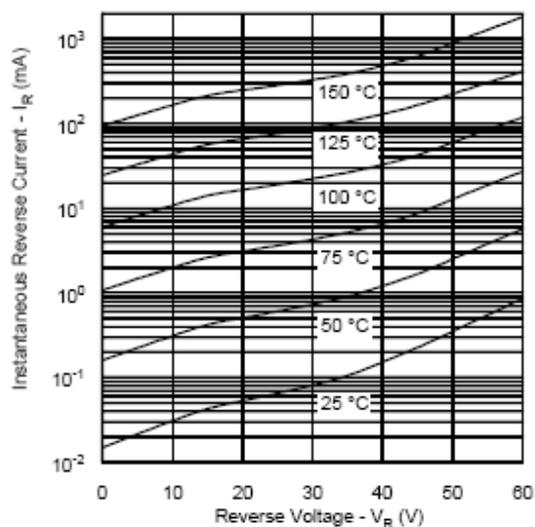
Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units	
Max. Junction Temperature	T_J	-	-55 to +150	$^{\circ}C$	
Max. Storage Temperature	T_{stg}	-	-55 to +150	$^{\circ}C$	
Maximum Thermal Resistance Junction to Case (per leg)	$R_{\theta JC}$	DC operation	0.20	$^{\circ}C/W$	
Maximum Thermal Resistance Junction to Case (per package)	$R_{\theta JC}$	DC operation	0.10	$^{\circ}C/W$	
Typical Thermal Resistance, case to Heat Sink	$R_{\theta cs}$	Mounting surface, smooth and greased	0.10	$^{\circ}C/W$	
Mounting Torque	T_M	-	Mounting Torque	24(min) 35(max)	Kg-cm
			Terminal Torque	35(min) 46(max)	
Approximate Weight	wt	-	79	g	
Case Style	PRM4 Non-Isolated				

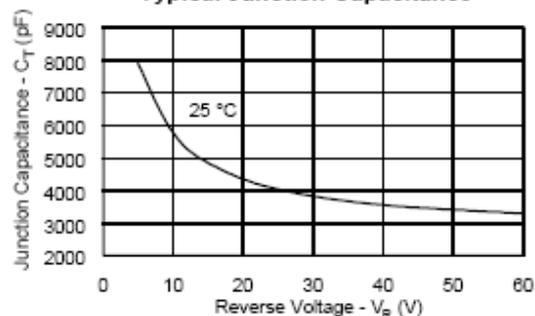
Typical Forward Characteristics



Typical Reverse Characteristics



Typical Junction Capacitance



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